PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4864802

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	LICENSE	

CONVEYING PARTY DATA

Name	Execution Date
CIMS HONG KONG CO.,LIMITED	08/18/2017

RECEIVING PARTY DATA

Name:	CAMTEK LTD	
Street Address:	RAMAT GABRIEL INDUSTRIAL PARK, POB 544	
City:	MIGDAL HAEMEK	
State/Country:	ISRAEL	
Postal Code:	23150	

PROPERTY NUMBERS Total: 3

Property Type	Number
Application Number:	12678148
Application Number:	12524002
Application Number:	10508527

CORRESPONDENCE DATA

Fax Number: (703)683-4707

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 7038385568
Email: oren@i-p.co.il
Correspondent Name: OREN RECHES

Address Line 1: 211 NORTH UNION STREET, SUITE 100

Address Line 4: ALEXANDRIA, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	9071
NAME OF SUBMITTER:	OREN RECHES
SIGNATURE:	/OREN RECHES/
DATE SIGNED:	03/14/2018

Total Attachments: 3

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PATENT 504818067 REEL: 045583 FRAME: 0788

LICENSE AGREEMENT

This License Agreement (this "Agreement") is made by and between Camtek Ltd., (in Hebrew:ממטק בע"מ), a limited liability company duly organized and existing under the Laws of the State of Israel ("Camtek") and CIMS Hong Kong Co., Limited., a limited liability company duly organized and existing under the Laws of Hong Kong ("CIMS");

WHEREAS, Camtek, CIMS and CIT are parties to the Intellectual Property Transfer and License Agreement, dated 18 August, 2017 ("IP Agreement"), NOW therefore, parties agree as follows:

FOR good and valuable consideration, CIMS grant Camtek and its Subsidiaries a license to practice and exploit each item of the following patents: (1) exclusive in the Semiconductor Business field, and (2) non-exclusive in all fields other than the PCB Business field and the Semiconductor Business field.

The main terms of the license granted hereunder are listed as below:

- 1. Type of the license: royalty free.
- 2. Payment method: fully paid-up.
- 3. Duration of the license: full term of the patent.
- 4. Teritory of the license: the United States of America.

In this Agreement, the Semiconductor Business means, collectively, the optical inspection and metrology solutions for semiconductor wafers and/or devices, including semiconductors-related inspection and metrology applications, such as (1) advanced glass substrates, glass carriers and fan-out technologies that include active components,(2) interposers, (3) substrates with active components or (4) the inspection of optical lenses. In these definitions, the terms "substrate" or "advanced substrate" each means - substrate that is used as an IC carrier.

The PCB Business means, collectively, the business which consists of (i) all sold products and solutions of the sold PCB BU of Camtek, and of (ii) the development, manufacture, repair and sale of: (1) AOI products, (2) AVI products, and (3) other capital equipment products; all for optical inspection and solutions for printed circuit boards and/or for bare advanced substrates production (except substrates that are included in the Semiconductors Business definition) and/or quality control process steps in connection with such products. In these definitions, the terms "substrate" or "advanced substrate" each means - substrate that is used as an IC carrier

Patents to be licensed hereunder are specified as follows:

Title	App Number	Priority Date	Internal Ref. No.	Status
M&S For Controlling A Manufacturing Process	12/678148	18-Oct-10	3017/43-US	Granted

IN WITNESS WHEREOF, the parties hereto have caused this License Agreement to be executed by duly authorized officer:

CIMS Hong Kong Co., Limited	Camtek Ltd.
YUN GEORGE CUN	Moshe Eisenberg
Authorized Officer Name	Authorized Officer Name
Signature	Signature
Date	Date

9071-US

Title	App Number	Priority Date	Internal Ref. No.	Status
Method and system for supporting a moving optical component on a sloped portion	12/524002	29-Dec-09	3017/10.1-US	Granted
A method for storing layers' information of a layer-made object	10/508527	25-Jul-05	3017/55-US	Granted

If any inconsistencies occur between this Agreement and the IP Agreement, the terms of the IP Agreement shall prevail.

(Signature page follows)

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PATENT REEL: 045583 FRAME: 0791

RECORDED: 03/14/2018